

## PATENT ASSIGNMENT

Electronic Version v1.1  
 Stylesheet Version v1.1

SUBMISSION TYPE:	NEW ASSIGNMENT										
NATURE OF CONVEYANCE:	ASSIGNMENT										
CONVEYING PARTY DATA											
<table border="1"> <thead> <tr> <th>Name</th> <th>Execution Date</th> </tr> </thead> <tbody> <tr> <td>Olivier Le Neel</td> <td>03/26/2013</td> </tr> <tr> <td>Ravi Shankar</td> <td>03/27/2013</td> </tr> <tr> <td>Suman Cherian</td> <td>03/27/2013</td> </tr> </tbody> </table>		Name	Execution Date	Olivier Le Neel	03/26/2013	Ravi Shankar	03/27/2013	Suman Cherian	03/27/2013		
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RECEIVING PARTY DATA											
<table border="1"> <tr> <td>Name:</td> <td>STMicroelectronics Pte Ltd.</td> </tr> <tr> <td>Street Address:</td> <td>28 Ang Mo Kio Industrial Park 2</td> </tr> <tr> <td>City:</td> <td>Singapore</td> </tr> <tr> <td>State/Country:</td> <td>SINGAPORE</td> </tr> <tr> <td>Postal Code:</td> <td>569508</td> </tr> </table>		Name:	STMicroelectronics Pte Ltd.	Street Address:	28 Ang Mo Kio Industrial Park 2	City:	Singapore	State/Country:	SINGAPORE	Postal Code:	569508
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PROPERTY NUMBERS Total: 1											
<table border="1"> <thead> <tr> <th>Property Type</th> <th>Number</th> </tr> </thead> <tbody> <tr> <td>Application Number:</td> <td>13853801</td> </tr> </tbody> </table>		Property Type	Number	Application Number:	13853801						
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CORRESPONDENCE DATA											
Fax Number: 2066826031 <i>Correspondence will be sent via US Mail when the fax attempt is unsuccessful.</i> Phone: 206-622-4900 Email: MollyM@SeedIP.com Correspondent Name: Hayley J. Talbert Address Line 1: 701 Fifth Avenue Address Line 2: Suite 5400 Address Line 4: Seattle, WASHINGTON 98104											
ATTORNEY DOCKET NUMBER:	851663.569										
NAME OF SUBMITTER:	Hayley J. Talbert										
Signature:	/Hayley J. Talbert/										

Date:

04/19/2013

Total Attachments: 2

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## ASSIGNMENT

Application Number: 13/853,801

Application Country/Region: **United States of America**

Application Title: **MICROELECTRONIC ENVIRONMENTAL SENSING MODULE**

Assignee: **STMicroelectronics Pte Ltd.**

Assignee being a company, corporation, or juristic entity of: **Singapore**

Assignee's principal place of business: **28 Ang Mo Kio Industrial Park 2, Singapore 569508**

I, the below identified and undersigned inventor or co-inventor, as the case may be, of residence listed below, for and in consideration of good and valuable consideration, the receipt, sufficiency, and adequacy of which are hereby acknowledged, hereby transfer and assign to Assignee, its legal representatives, successors, and assigns, my entire right, title, and interest in and to the inventions for which the above identified patent application is made and describes (hereinafter referred to as "the Patent Rights"), together with any and all patents or patent applications anywhere worldwide to which any of the Patent Rights directly or indirectly claims priority, including but not limited to provisional applications thereof, or for which any of the Patent Rights directly or indirectly forms a basis for priority, together with all existing and/or future continuations, continuations-in-part, continuing prosecution applications, requests for continuing examinations, divisions, reissues, reexaminations, extensions, registrations, and foreign counterparts of any item in any of the foregoing, together with the right to sue for and be entitled to any damages, injunctive relief, and any other remedies of any kind for past, current, and future infringement thereof, together with all rights worldwide in the Patent Rights; said entire right, title, and interest, to be held and enjoyed by the Assignee for its own use and enjoyment and for the use and enjoyment of its legal representatives, successors, and assigns to the full end of the term for which the aforementioned rights may be granted anywhere in the world.

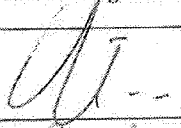

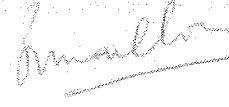
I hereby further agree to assist in and execute all documents needed now or in the future to perfect, obtain, and secure the aforementioned rights to Assignee, its legal representatives, successors, and assigns, for any jurisdiction in the world. At the expense of Assignee, or its legal representatives, successors, or assigns, I agree to assist in any legal proceedings, sign all lawful papers, make all lawful oaths, and generally do everything possible to aid Assignee, its legal representatives, successors, and assigns, to enforce the aforementioned rights in any and all countries and regions worldwide.

I hereby grant Assignee, along with the following Assignee representatives, the power to insert in this Assignment any further identification that may be necessary or desirable in order to comply with the rules for recordation of this document any place in the world: All practitioners at Customer Number 30423.

If there are co-inventors listed below, the signatures of all the inventor's need not appear on the same page, and each inventor may sign this Assignment in multiple counterparts, such that each separately signed counterpart of this Assignment constitutes an original Assignment for the inventor(s) that signed such counterpart. Assignee's counsel is authorized to insert the application number when it becomes available.

ST Docket Number: 12-AMK-0890US01  
851663.569

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Inventor Name	Residence (City, State, Country)	Inventor Signature	Date Signed
Olivier Le Neel	6 Cactus Drive Grande Vista Singapore 809685		26-7-17
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